

Automotive-grade N-channel 100 V, 5 mΩ typ., 107 A, STripFET™ F7 Power MOSFET in a PowerFLAT™ 5x6 package

Datasheet - production data

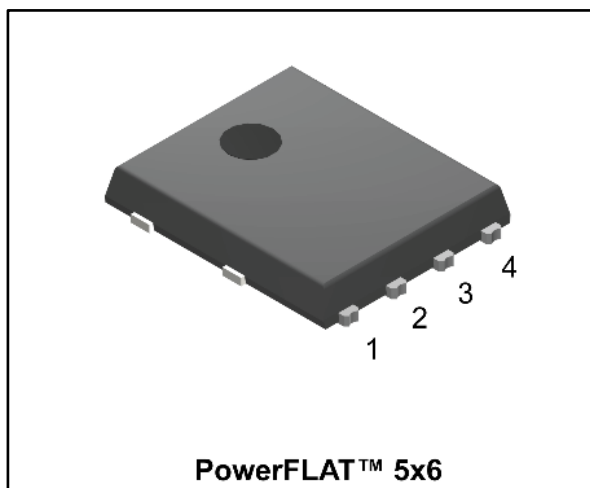
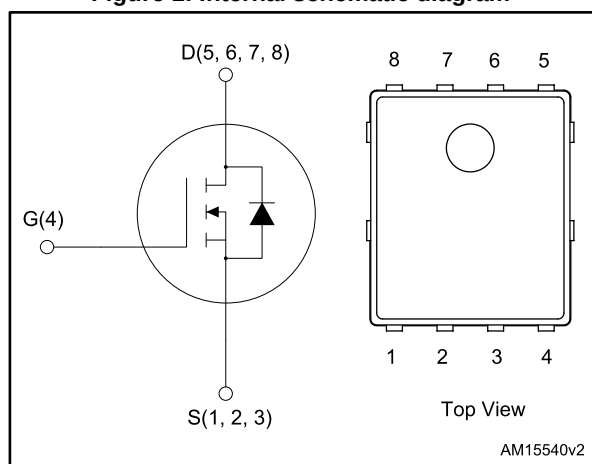


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max	I _D	P _{TOT}
STL115N10F7AG	100 V	6 mΩ	107 A	136 W



- AEC-Q101 qualified
- Among the lowest R_{DS(on)} on the market
- Excellent FoM (figure of merit)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness

Applications

- Switching applications

Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Table 1: Device summary

Order code	Marking	Package	Packaging
STL115N10F7AG	115N10F7	PowerFLAT™ 5x6	Tape and reel

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	100	V
V_{GS}	Gate-source voltage	± 20	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$	107	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$	75	A
$I_{DM}^{(1)}$	Drain current (pulsed)	428	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^{\circ}\text{C}$	136	W
$E_{AS}^{(2)}$	Single pulse avalanche energy	490	mJ
T_J	Operating junction temperature range	-55 to 175	$^{\circ}\text{C}$
T_{stg}	Storage temperature range		

Notes:

⁽¹⁾Pulse width limited by safe operating area

⁽²⁾Starting $T_J = 25\text{ }^{\circ}\text{C}$, $I_D = 18\text{ A}$, $V_{DD} = 50\text{ V}$

Table 3: Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.1	$^{\circ}\text{C/W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	31.3	$^{\circ}\text{C/W}$

Notes:

⁽¹⁾When mounted on FR-4 board of 1inch², 2oz Cu, $t < 10\text{ s}$

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4: On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	V _{GS} = 0 V, I _D = 250 μA	100			V
I _{DSS}	Zero gate voltage drain current	V _{GS} = 0 V, V _{DS} = 100 V			1	μA
		V _{GS} = 0 V, V _{DS} = 100 V, T _C = 125 °C ⁽¹⁾			10	
I _{GSS}	Gate body leakage current	V _{DS} = 0 V, V _{GS} = 20 V			100	nA
V _{GS(th)}	Gate threshold voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.5		4.5	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 53 A		5	6	mΩ

Notes:

⁽¹⁾Defined by design, not subject to production test.

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input capacitance	V _{DS} = 50 V, f = 1 MHz, V _{GS} = 0 V	-	5600	-	pF
C _{oss}	Output capacitance		-	1200	-	pF
C _{rss}	Reverse transfer capacitance		-	50	-	pF
Q _g	Total gate charge	V _{DD} = 50 V, I _D = 107 A, V _{GS} = 10 V (see Figure 14: "Test circuit for gate charge behavior")	-	72.5	-	nC
Q _{gs}	Gate-source charge		-	35.5	-	nC
Q _{gd}	Gate-drain charge		-	15	-	nC

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 50 V, I _D = 53 A, R _G = 4.7 Ω, V _{GS} = 10 V (see Figure 13: "Test circuit for resistive load switching times" and Figure 18: "Switching time waveform")	-	33	-	ns
t _r	Rise time		-	38	-	ns
t _{d(off)}	Turn-off delay time		-	48	-	ns
t _f	Fall time		-	20	-	ns

Table 7: Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		107	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		428	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 53\text{ A}$, $V_{GS} = 0\text{ V}$	-		1.2	V
t_{rr}	Reverse recovery time	$I_{SD} = 107\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 80\text{ V}$, $T_j = 150\text{ }^{\circ}\text{C}$ (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	60		ns
Q_{rr}	Reverse recovery charge		-	96		nC
I_{RRM}	Reverse recovery current		-	3.2		A

Notes:⁽¹⁾Pulse width limited by safe operating area⁽²⁾Pulsed: pulse duration=300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2: Safe operating area

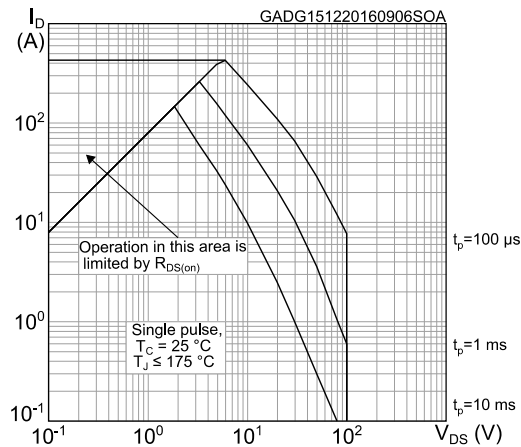


Figure 3: Thermal impedance

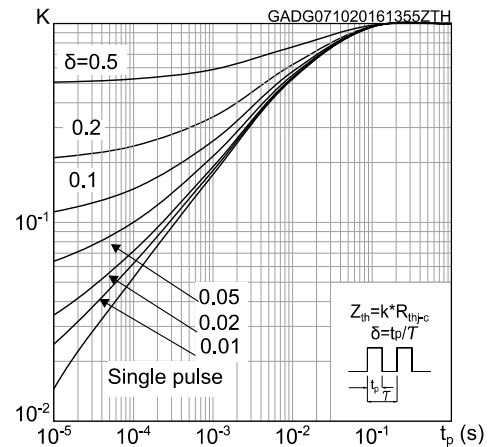


Figure 4: Output characteristics

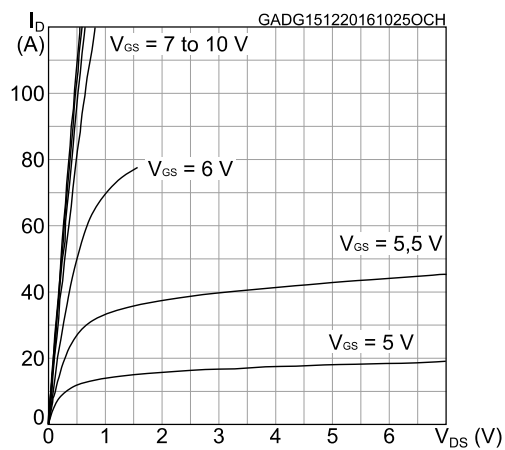


Figure 5: Transfer characteristics

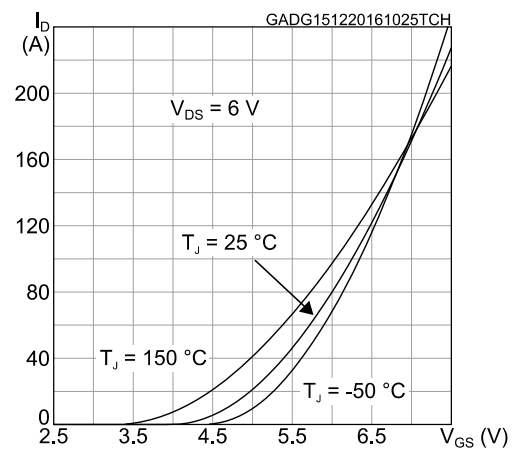


Figure 6: Gate charge vs gate-source voltage

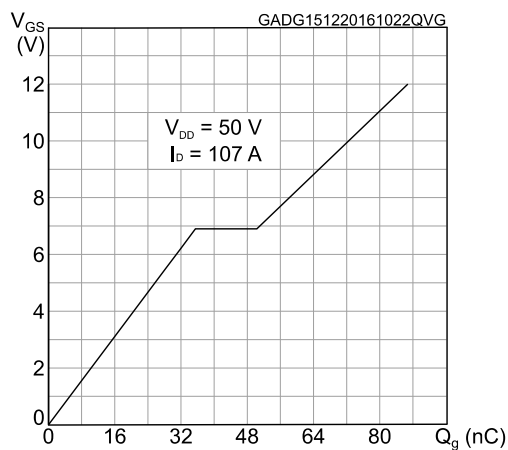


Figure 7: Static drain-source on-resistance

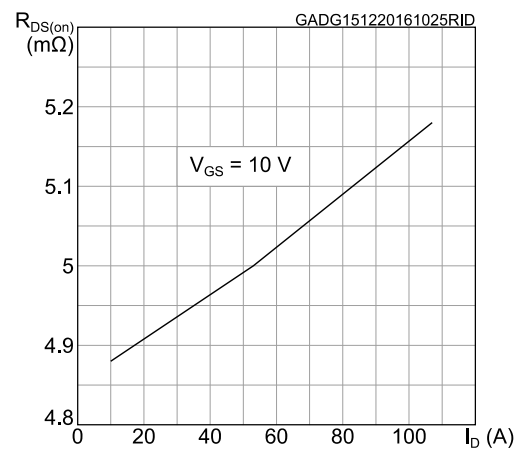


Figure 8: Capacitance variations

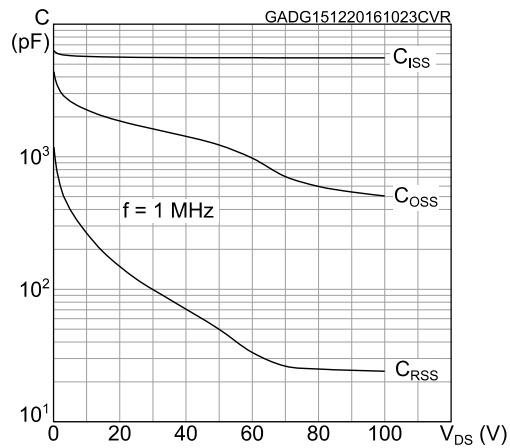


Figure 9: Normalized gate threshold voltage vs temperature

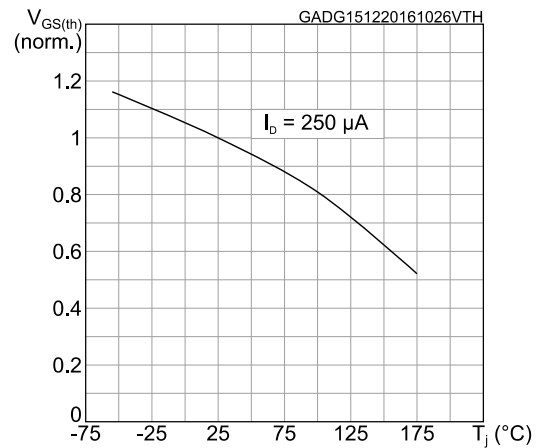


Figure 10: Normalized on-resistance vs temperature

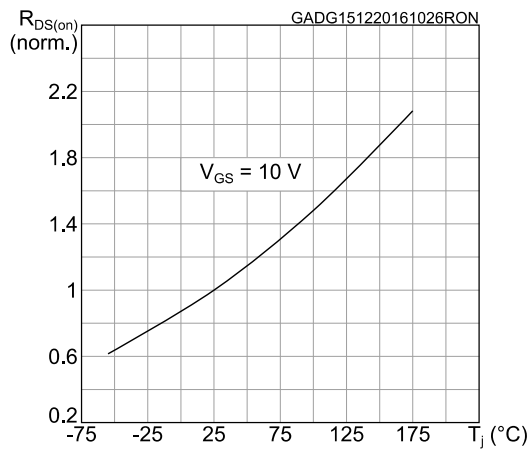
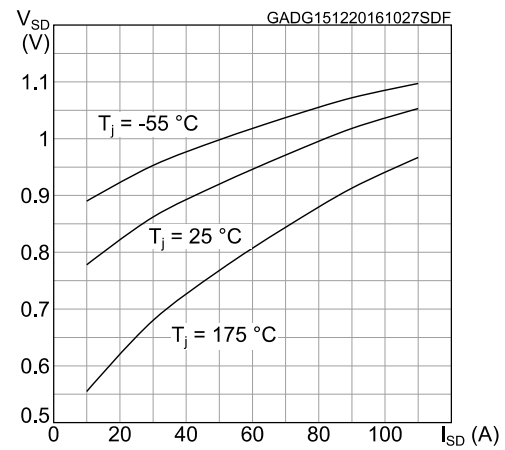
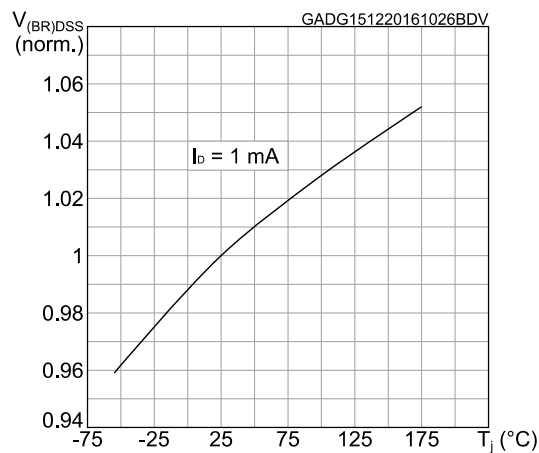


Figure 11: Source-drain diode forward characteristics

Figure 12: Normalized $V_{(BR)DSS}$ vs temperature

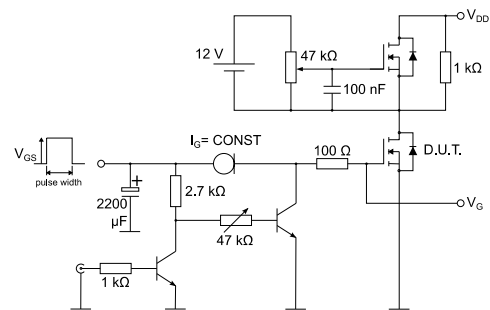
3 Test circuits

Figure 13: Test circuit for resistive load switching times



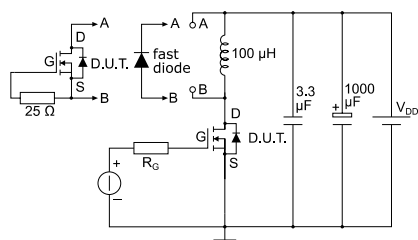
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Figure 14: Test circuit for gate charge behavior



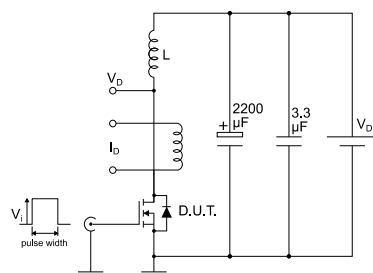
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Figure 15: Test circuit for inductive load switching and diode recovery times



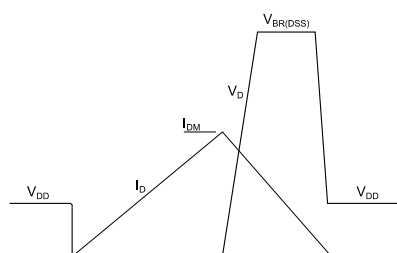
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Figure 16: Unclamped inductive load test circuit



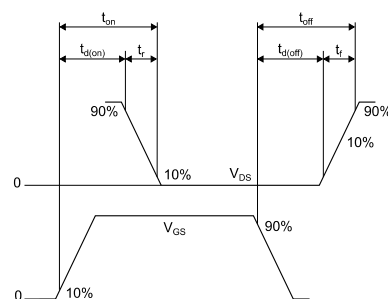
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Figure 17: Unclamped inductive waveform



AM01472v1

Figure 18: Switching time waveform



AM01473v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 PowerFLAT™ 5x6 WF type C package information

Figure 19: PowerFLAT™ 5x6 WF type C package outline

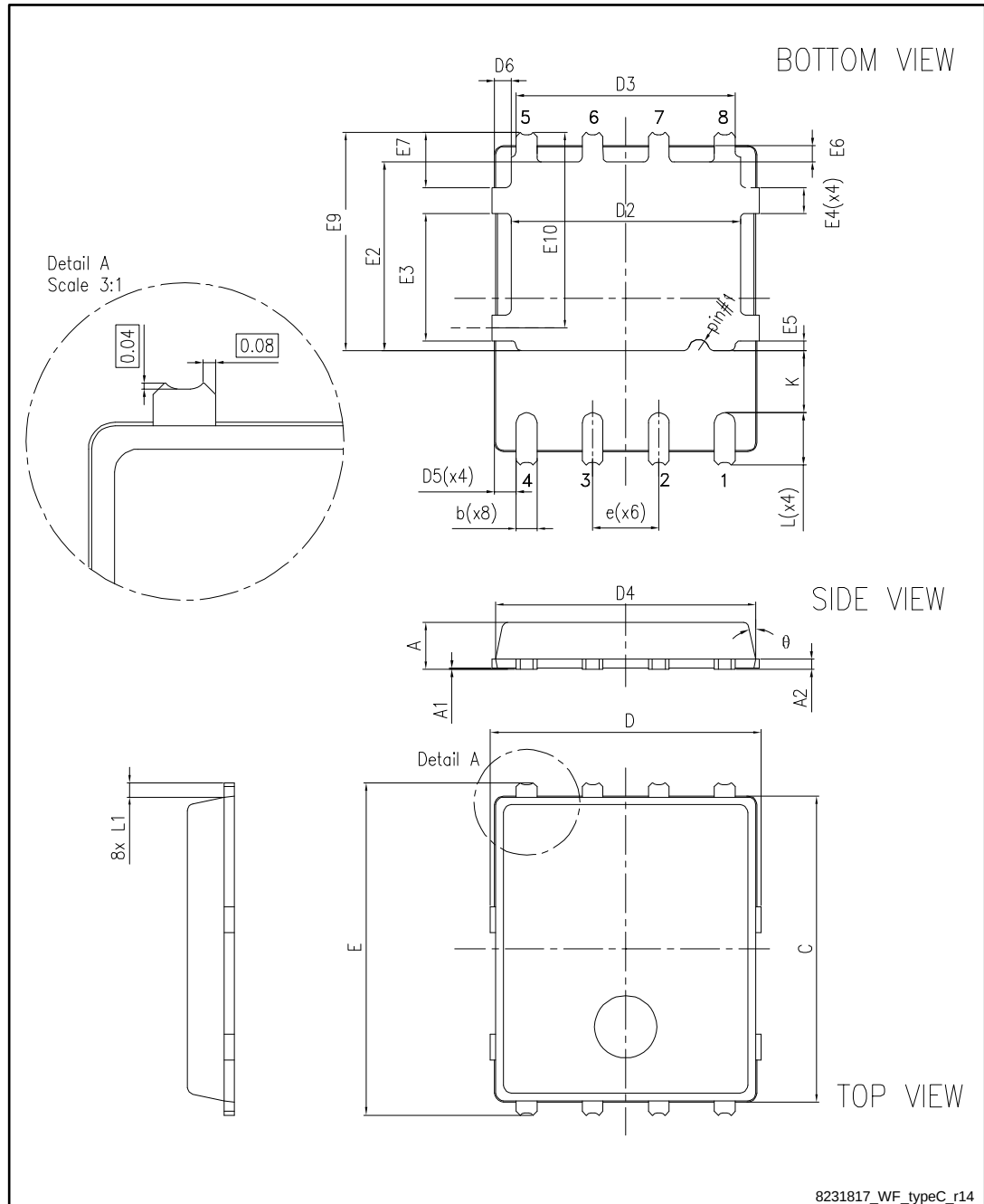
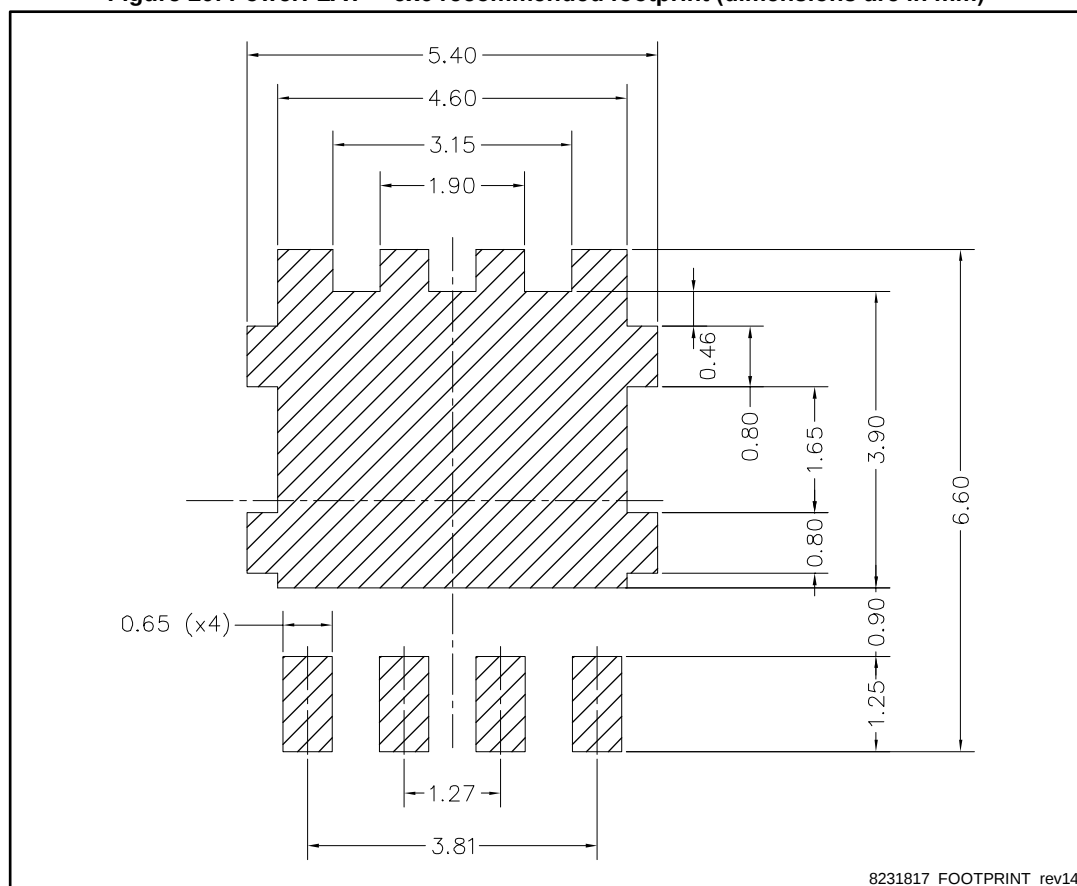


Table 8: PowerFLAT™ 5x6 WF type C mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.80	6.00	6.10
D	5.00	5.20	5.40
D2	4.15		4.45
D3	4.05	4.20	4.35
D4	4.80	5.00	5.10
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
e		1.27	
E	6.20	6.40	6.60
E2	3.50		3.70
E3	2.35		2.55
E4	0.40		0.60
E5	0.08		0.28
E6	0.20	0.325	0.45
E7	0.85	1.00	1.15
E9	4.00	4.20	4.40
E10	3.55	3.70	3.85
K	1.05		1.35
L	0.90	1.00	1.10
L1	0.175	0.275	0.375
θ	0°		12°

Figure 20: PowerFLAT™ 5x6 recommended footprint (dimensions are in mm)



4.2 PowerFLAT™ 5x6 packing information

Figure 21: PowerFLAT™ 5x6 WF tape (dimensions are in mm)

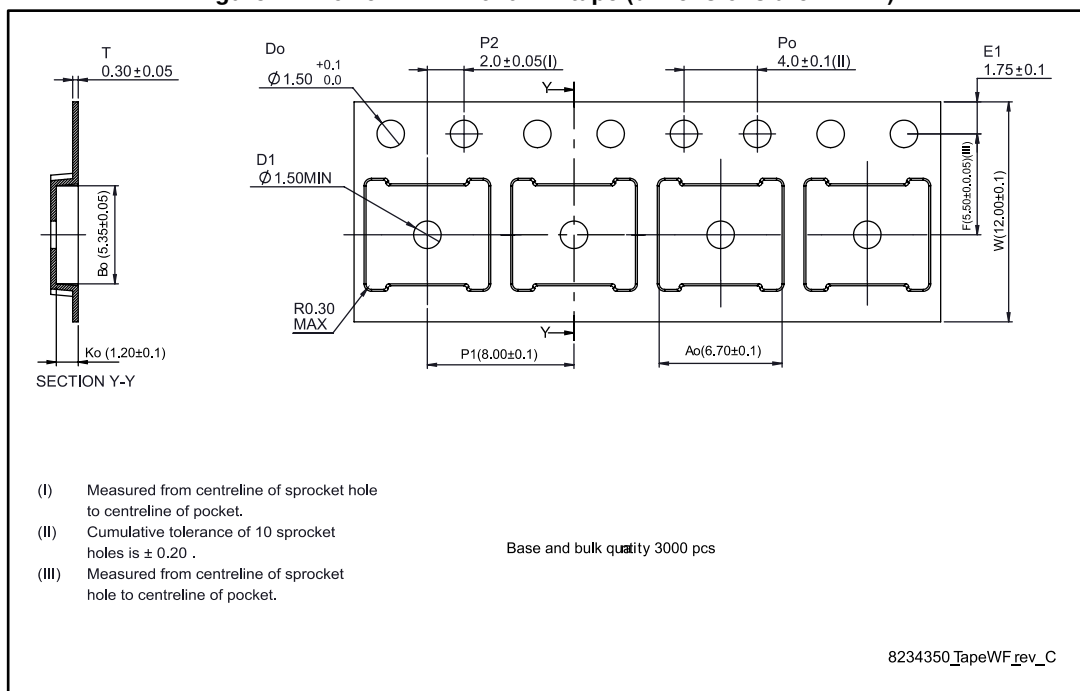


Figure 22: PowerFLAT™ 5x6 package orientation in carrier tape

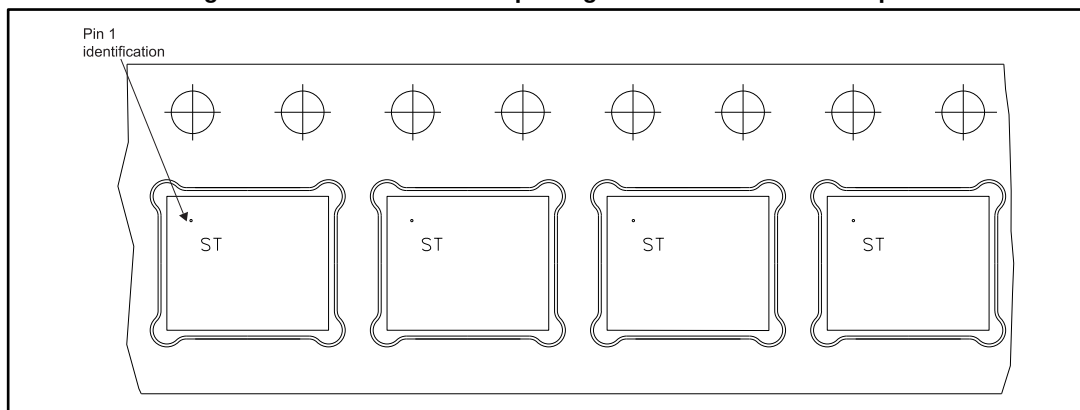
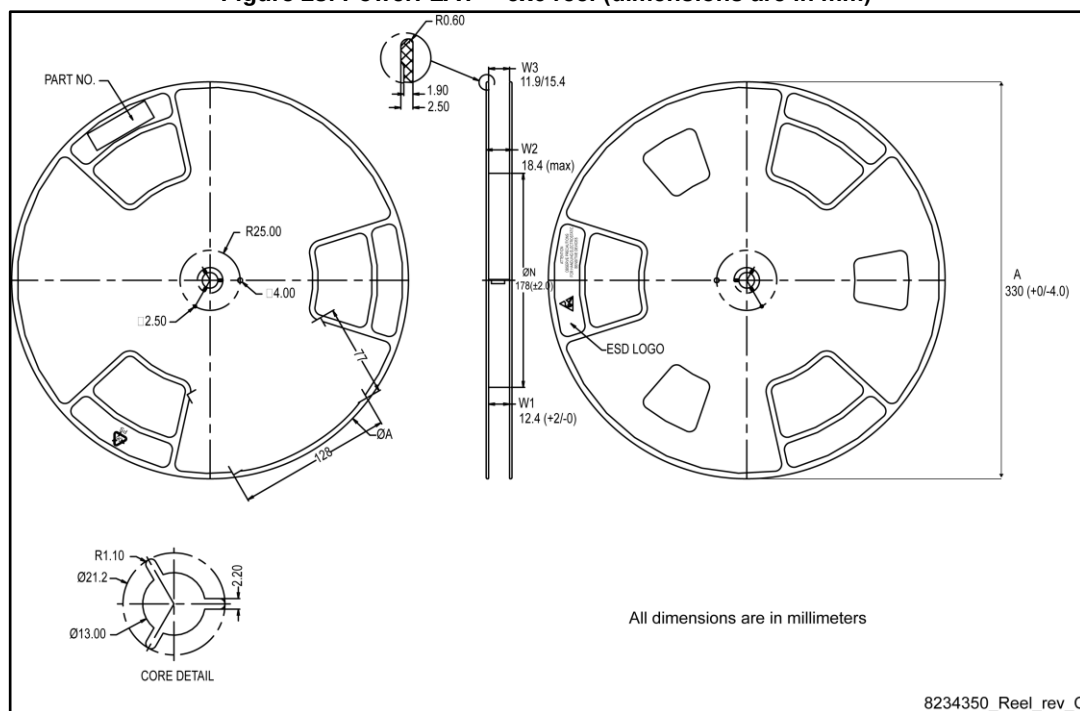


Figure 23: PowerFLAT™ 5x6 reel (dimensions are in mm)



5 Revision history

Table 9: Document revision history

Date	Revision	Changes
07-Oct-2016	1	First release.
15-Dec-2016	2	Datasheet status promoted from preliminary to production data. Updated features list on cover page. Updated Section 2: "Electrical characteristics" .

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